NPN Silicon Transistor

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	300	Vdc
Collector - Base Voltage	V _{CBO}	300	Vdc
Collector - Emitter Voltage	V _{CER}	300	Vdc
Emitter - Base Voltage	V _{EBO}	5.0	Vdc
Collector Current	I _C	100	mAdc
Total Power Dissipation up to T _A = 25°C	P _D	1.5	W
Storage Temperature Range	T _{stg}	-65 to +150	°C
Junction Temperature	TJ	150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

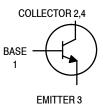
Device mounted on a glass epoxy printed circuit board 1.575 in. x 1.575 in. x 0.059 in.; mounting pad for the collector lead min. 0.93 in².



ON Semiconductor®

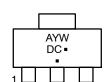
http://onsemi.com

NPN SILICON TRANSISTOR SURFACE MOUNT





MARKING DIAGRAM



SOT-223 (TO-261) CASE 318E STYLE 1

1

A = Assembly Location

/ = Year

V = Work Week

DC = Device Code • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
BF720T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
BF720T3G	SOT-223 (Pb-Free)	4000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristics	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V _(BR) CEO	300	-	Vdc
Collector-Base Breakdown Voltage $(I_C = 100 \mu Adc, I_E = 0)$	V _(BR) CBO	300	-	Vdc
Collector-Emitter Breakdown Voltage (I _C = 100 μ Adc, R _{BE} = 2.7 μ C)	V _(BR) CER	300	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = 10 \mu Adc, I_C = 0$)	V _{(BR)EBO}	5.0	-	Vdc
Collector-Base Cutoff Current $(V_{CB} = 200 \text{ Vdc}, I_E = 0)$	Ісво	-	10	nAdc
Collector-Emitter Cutoff Current $ \begin{array}{l} \text{(V}_{\text{CE}} = 250 \text{ Vdc, R}_{\text{BE}} = 2.7 \text{ k}\Omega) \\ \text{(V}_{\text{CE}} = 200 \text{ Vdc, R}_{\text{BE}} = 2.7 \text{ k}\Omega, T_{\text{J}} = 150 ^{\circ}\text{C)} \end{array} $	I _{CER}		50 10	nAdc μAdc
ON CHARACTERISTICS		-		•
DC Current Gain ($I_C = 25 \text{ mAdc}, V_{CE} = 20 \text{ Vdc}$)	h _{FE}	50	-	-
Collector-Emitter Saturation Voltage (I _C = 30 mAdc, I _B = 5.0 mAdc)	V _{CE(sat)}	-	0.6	Vdc
DYNAMIC CHARACTERISTICS		-		•
Current-Gain - Bandwidth Product ($I_C = 10 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 35 \text{ MHz}$)	f⊤	60	-	MHz
Feedback Capacitance ($V_{CE} = 30 \text{ Vdc}, I_{C} = 0, f = 1.0 \text{ MHz}$)	C _{re}	-	1.6	pF

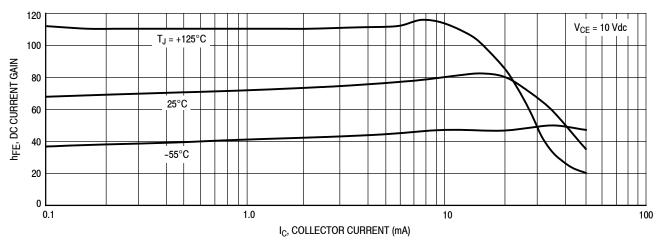


Figure 1. DC Current Gain

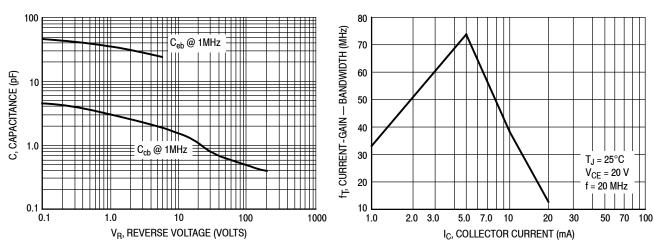
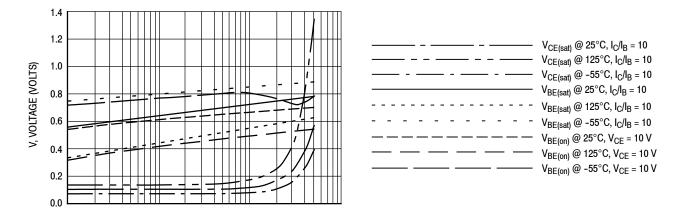


Figure 2. Capacitance



100

Figure 3. Current-Gain - Bandwidth

I_C, COLLECTOR CURRENT (mA)

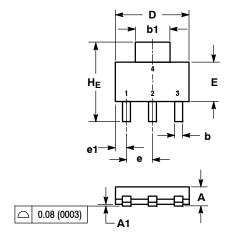
Figure 4. "ON" Voltages

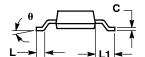
1.0

0.1

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 **ISSUE N**





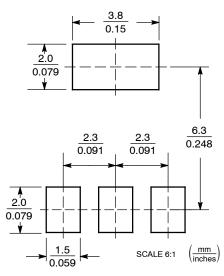
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	MOM	MAX	
Α	1.50	1.63	1.75	0.060	0.064	0.068	
A1	0.02	0.06	0.10	0.001	0.002	0.004	
b	0.60	0.75	0.89	0.024	0.030	0.035	
b1	2.90	3.06	3.20	0.115	0.121	0.126	
c	0.24	0.29	0.35	0.009	0.012	0.014	
D	6.30	6.50	6.70	0.249	0.256	0.263	
Е	3.30	3.50	3.70	0.130	0.138	0.145	
е	2.20	2.30	2.40	0.087	0.091	0.094	
e1	0.85	0.94	1.05	0.033	0.037	0.041	
L	0.20			0.008			
L1	1.50	1.75	2.00	0.060	0.069	0.078	
HE	6.70	7.00	7.30	0.264	0.276	0.287	
θ	0°	-	10°	0°	-	10°	

PIN 1. BASE 2. COLLE

- COLLECTOR 3. EMITTER

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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